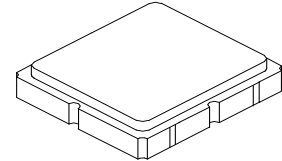


SF2317D

**611 MHz
SAW Filter**



SM3838-8

- **Low-loss SAW Filter**
- **Direct Match to 50 ohm Source and Load**
- **3.8 x 3.8 x 1.4 mm Surface-mount Package**
- **Complies with Directive 2002/95/EC (RoHS)**
- **Moisture Sensitivity Level: 1**

Absolute Maximum Ratings

Rating	Value	Units
Maximum Continuous Incident Power in Passband	+10	dBm
Maximum DC Voltage on any Non-ground Terminal	3	VDC
Operating Temperature Range	0 to +50	°C
Storage Temperature Range in Tape and Reel	-30 to +85	°C
Suitable for Lead-free Soldering - Maximum Soldering Profile	260 °C for 30 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			611		MHz
Insertion Loss, 608 to 614 MHz	IL			1.7	2.7	dB
Amplitude Ripple, 608 to 614 MHz				0.5	1.2	dB _{P-P}
Return Loss, 608 to 614 MHz			10	14		dB
Rejection Referenced to 0 dB:						dB
DC to 580 MHz			45	47		
736 to 792 MHz			45	52		
792 to 1000 MHz			40	47		
1000 to 2300 MHz			20	25		
2300 to 3000 MHz			12	18		

Case Style	SM3838-8 3.8 x 3.8 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	A76, YWWS					
Standard Reel Quantity	Reel Size 7 Inch					500 Pieces/Reel
	Reel Size 13 Inch					3000 Pieces/Reel

Electrical Connections

Connection	Terminals
Input Port	2
Output Port	6
Ground	All others

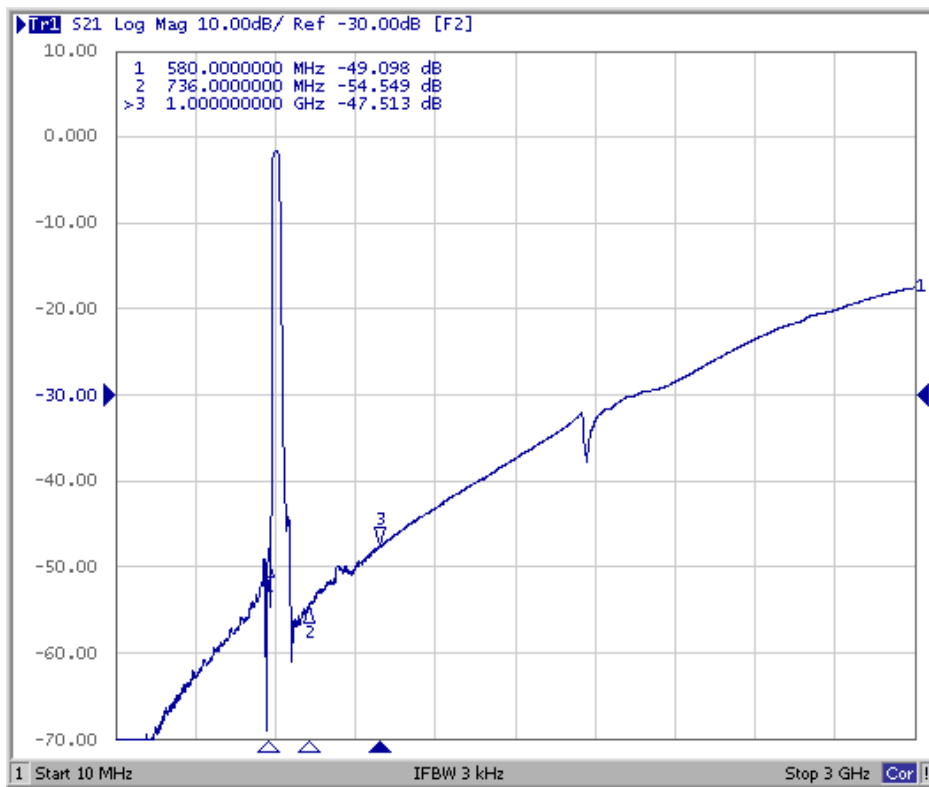
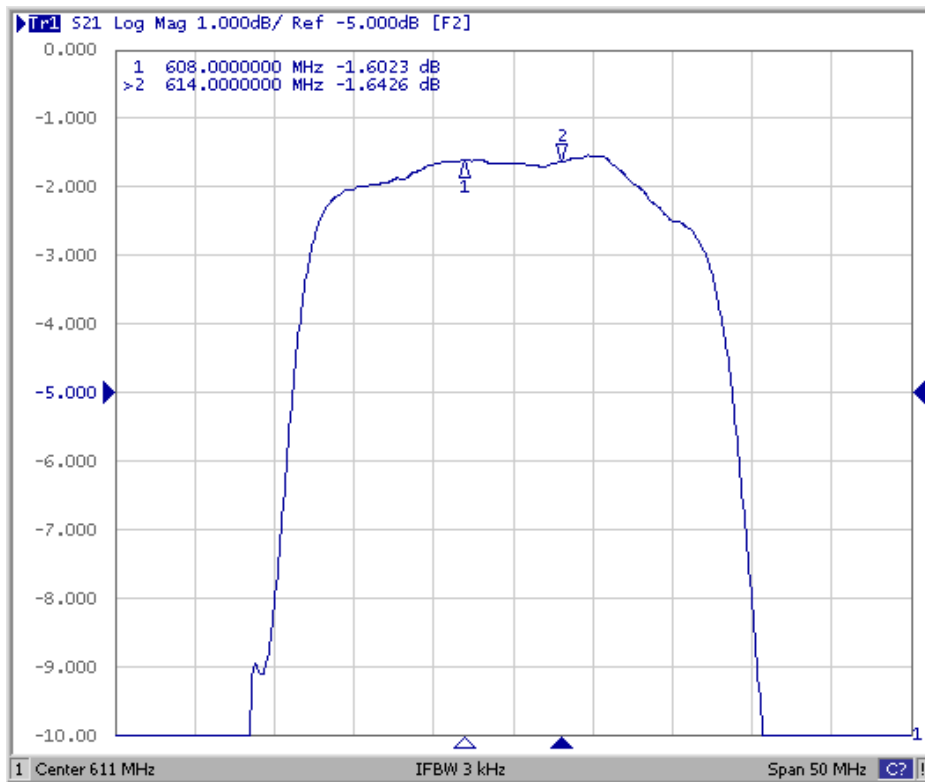


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

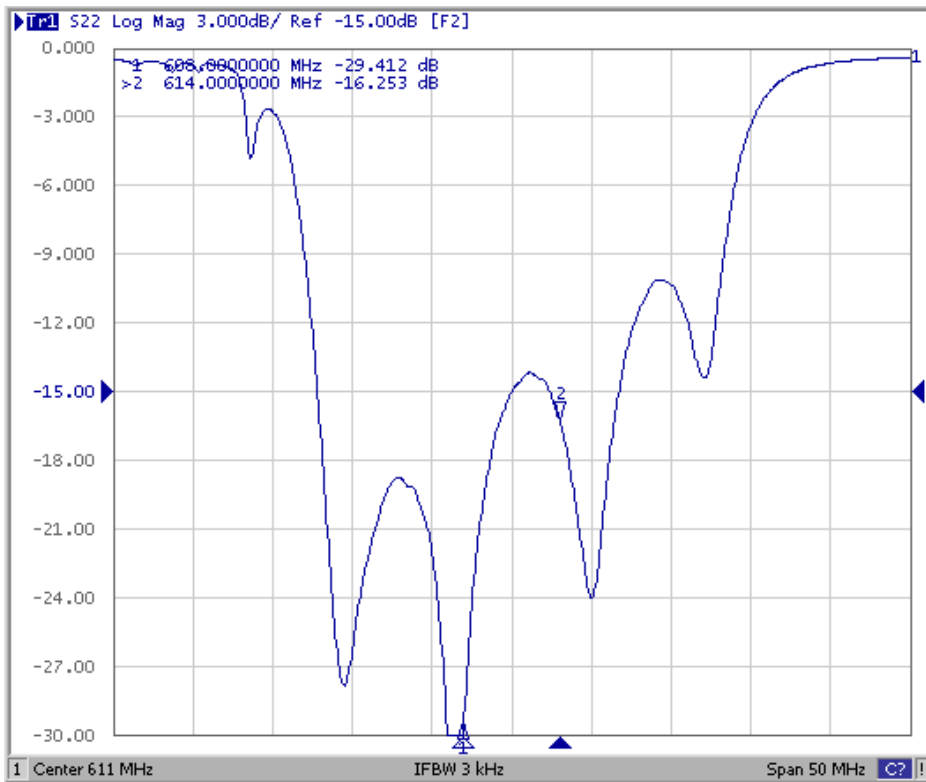
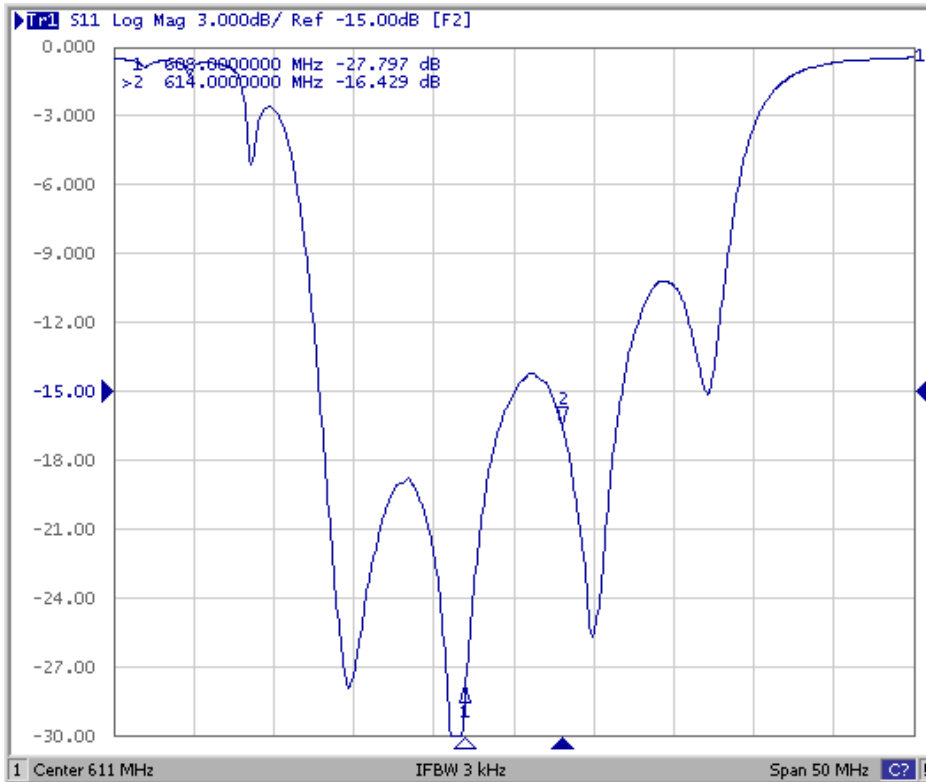
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.
3. RoHS compliant from the first date of manufacture.

Filter Response Plots



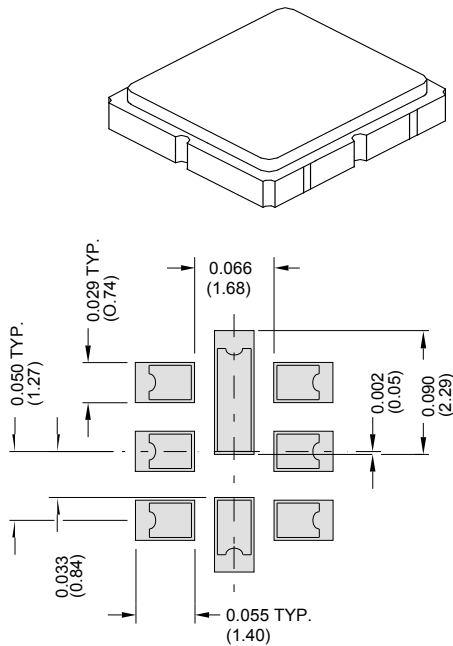
Return Loss Plots



SM3838-8 Case

8-Terminal Ceramic Surface-mount Case

3.8 X 3.8 mm Nominal Footprint



Typical PCB Land Footprint

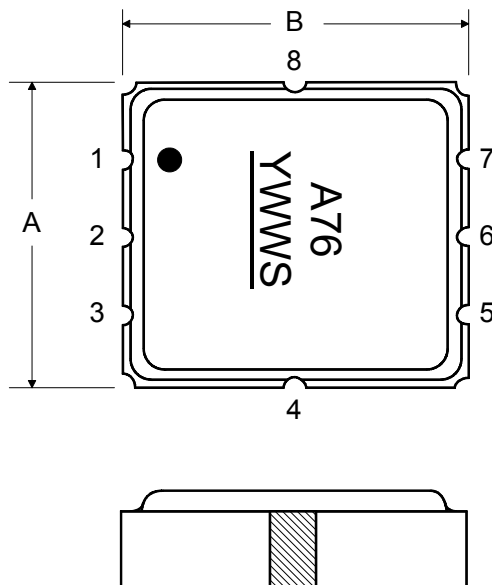
Case Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	3.6	3.8	4.0	0.142	0.150	0.157
B	3.6	3.8	4.0	0.142	0.150	0.157
C	1.05	1.20	1.40	0.041	0.047	0.055
D	0.95	1.10	1.25	0.037	0.043	0.049
E	0.90	1.00	1.10	0.035	0.040	0.043
F	0.50	0.60	0.70	0.020	0.024	0.028
G	2.39	2.54	2.69	0.090	0.100	0.110
H	1.40	1.75	2.05	0.055	0.069	0.080

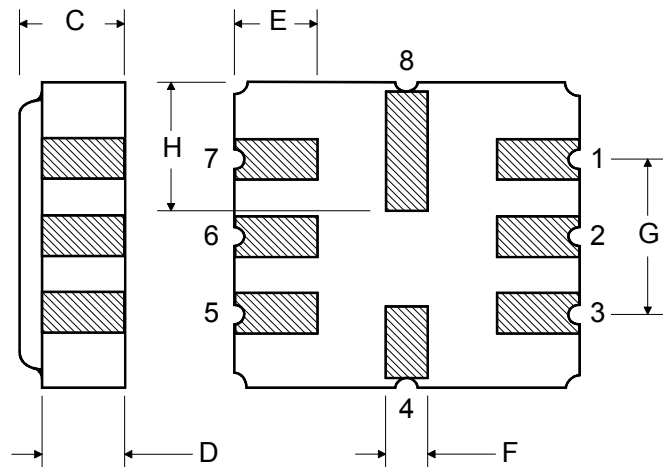
Materials

Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic

TOP VIEW

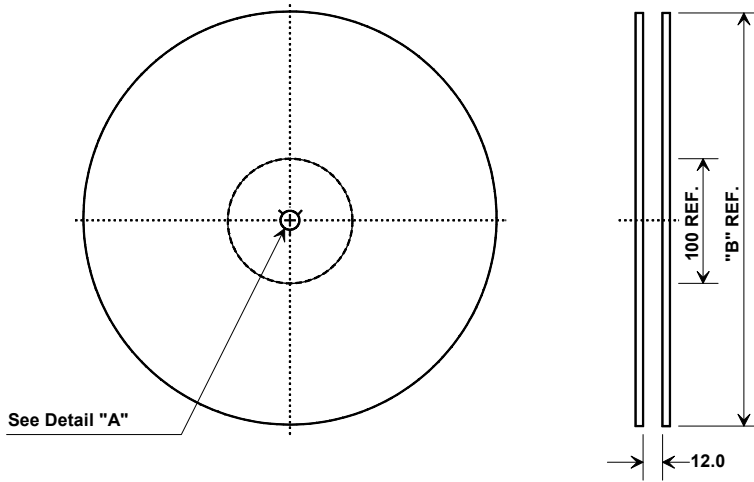


BOTTOM VIEW

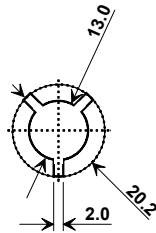


Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481

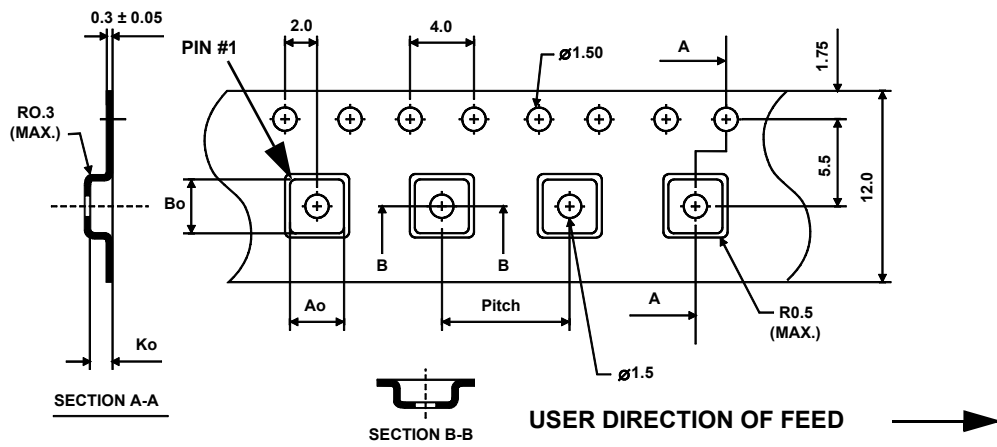


"B"		Quantity Per Reel
Nominal Size		
Inches	millimeters	
7	178	500
13	330	3000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	4.25 mm
Bo	4.25 mm
Ko	1.30 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

